PMP11099 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	Package
C1, C2, C3, C4	4	4.7uF	C3225X7S2A475M200AB	TDK	CAP, CERM, 4.7uF, 100V, +/-20%, X7S, 1210	1210
C5	1	1000pF	C1608X7R1H102K	TDK	CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0603	0603
C6, C14	2	0.1uF	C1608X7R1H104K	TDK	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603
C7	1	39pF	C1608C0G1H390J	TDK	CAP, CERM, 39 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C8	1	6800pF	C1608C0G1E682J	TDK	CAP, CERM, 6800 pF, 25 V, +/- 5%, C0G/NP0, 0603	0603
C9	1	4.7uF	GRM21BR71C475KA73L	MuRata	CAP, CERM, 4.7 µF, 16 V, +/- 10%, X7R, 0805	0805
C10	1	470uF	6SVP470M	Sanyo	CAP, OS-CON, 470 µF, 6.3 V, +/- 20%, 0.015 ohm, 8x11.9 SMD	8x11.9
C11	1	10uF	GRM31CR71C106MAC7	MuRata	CAP, CERM, 10 µF, 16 V, +/- 20%, X7R, 1206	1206
C12	1	1000pF	C1608X7R2A102M	TDK	CAP, CERM, 1000 pF, 100 V, +/- 20%, X7R, 0603	0603
C13	1	0.1uF	GRM188R72A104KA35D	MuRata	CAP, CERM, 0.1 µF, 100 V, +/- 10%, X7R, 0603	0603
C15	1	1uF	C1608X5R1C105K	TDK	CAP, CERM, 1 µF, 16 V, +/- 10%, X5R, 0603	0603
C16	1	2200pF	C1608C0G1H222J	TDK	CAP, CERM, 2200 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
J1, J4	2		ED555/2DS	On-Shore Tech	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm
J2, J3	2		PEC02SAAN	Sullins	Header, 100mil, 2x1, Tin, TH	Header, 2 PIN, 100mil, Tin
L1	1	15uH	XAL1513-153MEB	Coilcraft	Inductor, Shielded, Composite, 15 µH, 22 A, 0.0068 ohm, SMD	15.4 x 13 x 16.4mm
Q1	1	100V	CSD19534Q5A	Texas Instruments	MOSFET, N-CH, 100V, 15nC, 0.0124 ohm, SON 5x6mm	SON 5x6mm
Q2	1	100V	CSD19532Q5B	Texas Instruments	MOSFET, N-CH, 100 V, 17 A, SON 5x6mm	SON 5x6mm
R1, R2	2	301k	CRCW0603301KFKEA	Vishay-Dale	RES, 301 k, 1%, 0.1 W, 0603	0603
R3	1	15.0k	CRCW060315K0FKEA	Vishay-Dale	RES, 15.0 k, 1%, 0.1 W, 0603	0603
R4	1	30.1k	CRCW060330K1FKEA	Vishay-Dale	RES, 30.1 k, 1%, 0.1 W, 0603	0603
R5	1	4.7	CRCW06034R70JNEA	Vishay-Dale	RES, 4.7, 5%, 0.1 W, 0603	0603
R6, R7	2	2.2	CRCW06032R20JNEA	Vishay-Dale	RES, 2.2 ohm, 5%, 0.1W, 0603	0603
R8	1	2.70	ERJ-8RQF2R7V	Panasonic	RES, 2.70, 1%, 0.25 W, 1206	1206
R9	1	20.0k	CRCW060320K0FKEA	Vishay-Dale	RES, 20.0 k, 1%, 0.1 W, 0603	0603
R10, R11	2	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
R12	1	14.7k	CRCW060314K7FKEA	Vishay-Dale	RES, 14.7 k, 1%, 0.1 W, 0603	0603
R13	1				RES, open, 0603	0603
R14	1	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	0603
R15	1	6.81k	CRCW06036K81FKEA	Vishay-Dale	RES, 6.81 k, 1%, 0.1 W, 0603	0603
R16	1	49.9k	CRCW060349K9FKEA	Vishay-Dale	RES, 49.9 k, 1%, 0.1 W, 0603	0603
R17	1	3.01k	CRCW06033K01FKEA	Vishay-Dale	RES, 3.01 k, 1%, 0.1 W, 0603	0603
R18	1	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9, 1%, 0.1 W, 0603	0603
TP1, TP3, TP4, TP5, TP7, TP8	6	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP2, TP6	2	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
U1	1		TPS40170RGY	Texas Instruments	4.5-v to 60-v wide-input synchronous PWM buck controller, RGY0020A	RGY0020A

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265